# Embedded MXM Modules
# NVIDIA Blackwell Architecture

## Mobile PCI Express Modules with NVIDIA Embedded GPUs

NVIDIA RTX PRO



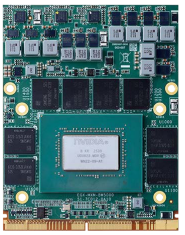
• EGX-MXM-BW500



• EGX-MXM-BW2000



• EGX-MXM-BW4000



• EGX-MXM-BW5000

## Features

- NVIDIA Blackwell architecture
- Standard MXM 3.1 Type A/B form factor
- PCIe Gen 5 up to x16 interface
- Up to 10,496 CUDA® Cores, 80 RT Cores, and 328 Tensor Cores
- Up to 49.8 TFLOPS peak FP32 performance
- Up to 24GB GDDR7 memory, 256-bit
- Up to 896GB/s memory bandwidth
- Support up to 4xDP 1.4a displays, 150W TGP
- 5-year Availability

## Ordering Information

| | |
|---|---|
| EGX-MXM-BW500 | Embedded NVIDIA RTX PRO 500 Blackwell, MXM 3.1 Type A, 82 x 70mm, PCIe Gen5 x8 |
| EGX-MXM-BW2000 | Embedded NVIDIA RTX PRO 2000 Blackwell, MXM 3.1 Type A, 82 x 70mm, PCIe Gen5 x8 |
| EGX-MXM-BW4000 | Embedded NVIDIA RTX PRO 4000 Blackwell, MXM 3.1 Type B, 82 x 105mm, PCIe Gen5 x16 |
| EGX-MXM-BW5000 | Embedded NVIDIA RTX PRO 5000 Blackwell, MXM 3.1 Type B, 82 x 105mm, PCIe Gen5 x16 |

## Optional Accessories

### Thermal Solutions

| | |
|---|---|
| THSF-MXMA-BW | Blackwell Type A active thermal solution (active cooler) |
| THSF-MXMB-BW | Blackwell Type B active thermal solution (active cooler) |
| THSP-MXMA-BW | Blackwell Type A active thermal solution (Heat Spreader) |
| THSP-MXMB-BW | Blackwell Type B active thermal solution (Heat Spreader) |

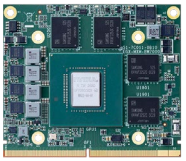
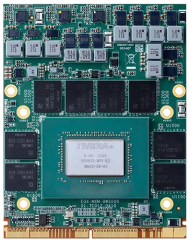
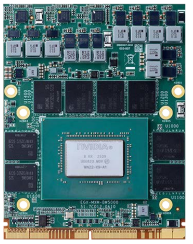
### Interposer Card

| | |
|---|---|
| EGX-MXM-AD | Embedded Graphics converter, MXM 3.1/3.0 to PCIe |



Distribuída no Brasil pela LRI | vendas@lri.com.br | 51 2129-3000

## Specifications

| Model Name | EGX-MXM-BW500 | EGX-MXM-BW2000 | EGX-MXM-BW4000 | EGX-MXM-BW5000 |
|---|---|---|---|---|
| **Graphic Core** | | | | |
| Graphic Architecture | NVIDIA® RTX PRO™ 500 Blackwell | NVIDIA® RTX PRO™ 2000 Blackwell | NVIDIA® RTX PRO™ 4000 Blackwell | NVIDIA® RTX PRO™ 5000 Blackwell |
| Memory | 6GB GDDR7 memory, 96-bit, Bandwidth: 288GB/s | 8GB GDDR7 memory, 128-bit, Bandwidth: 384GB/s | 16GB GDDR7 memory 256-bit Bandwidth 896GB/s | 24GB GDDR7 memory 256-bit Bandwidth 896GB/s |
| ECC Support | No | Yes | Yes | Yes |
| **GPGPU Computing** | | | | |
| CUDA® Cores | 1,792 CUDA® Cores, 9.2 TFLOPS Peak FP32 Performance | 3,328 CUDA® Cores, 17.7 TFLOPS Peak FP32 Performance | 7,680 CUDA® Cores 38.7 TFLOPS Peak FP32 Performance | 10,496 CUDA® Cores 49.8 TFLOPS Peak FP32 Performance |
| Tensor Cores | 56 | 104 | 240 | 328 |
| RT Cores | 14 | 26 | 60 | 80 |
| Compute API | CUDA® Toolkit 8.0 and above, CUDA® Compute version 8 and above, OpenCL™ 1.2 | | | |
| Graphics API | DirectX® 12.1, OpenGL® 4.6 | | | |
| **Display** | | | | |
| Display Outputs | 3x DP 2.1a | 3x DP 2.1a | 4x DP 2.1a | 4x DP 2.1a |
| | HDMI 2.1, 4K at 120Hz or 8K at 60Hz with 10-bit color depth | | | |
| Interface | PCIe Gen4/5 x8 | PCIe Gen4/5 x8 | PCIe Gen 4/5 x16 | PCIe Gen4/5 x16 |
| **Mechanicals** | | | | |
| Dimensions | 82 (W) x 70 (D) x 4.8 (H) mm | | 82 (W) x 105 (D) x 4.8 (H) mm | |
| Form Factor | Standard MXM 3.1 Type A | | Standard MXM 3.1 Type B | |
| **Environmental** | | | | |
| Operating Temperature | Standard: 0˚C – 55˚C Extended Temperature: -40˚C – 85˚C* | | | Standard: 0˚C–45˚C Extended Temperature: -40˚C – 85˚C* |
| Module Power Consumption | 60W Optional: 35W-60W | 60W Optional: 45W-100W | 115W Optional: 80W-150W | 115W Optional: 95W-150W |
| **SW Support** | | | | |
| OS Support | Windows 11, 10 & Linux Drivers, 64-bit | | | |

*For detailed support regarding wide-temperature specifications, please contact your account manager.

NVIDIA Preferred Partner

All products and company names listed are trademarks or trade names of their respective companies. Updated Jun. 29 2026. © 2026 ADLINK Technology, Inc. All Rights Reserved. All pricing and specifications are subject to change without further notice.